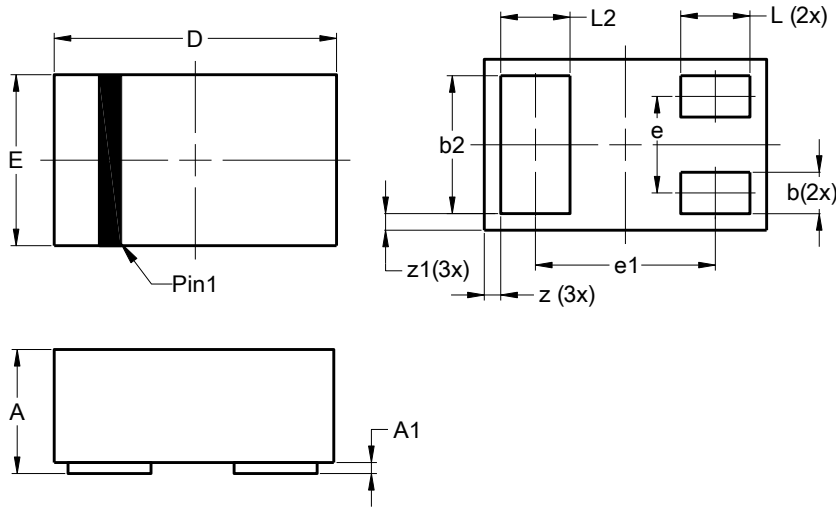


**Package Outline Dimensions**

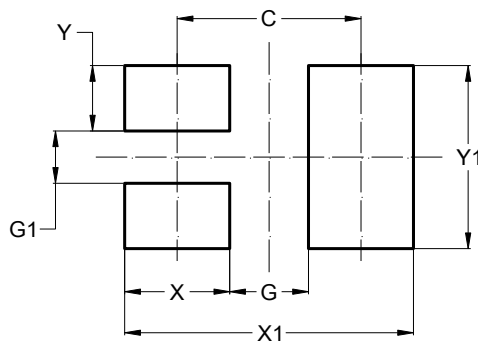
X1-DFN1006-3 (Type SA)



X1-DFN1006-3 (Type SA)			
Dim	Min	Max	Typ
A	0.400	0.500	--
A1	--	0.050	--
b	0.100	0.200	0.150
b2	0.450	0.550	0.500
D	0.990	1.050	1.020
E	0.590	0.650	0.620
e	0.350 BSC		
e1	0.650 BSC		
L	0.200	0.300	0.250
L2	0.200	0.300	0.250
z	0.020	0.100	0.060
z1	0.020	0.100	0.060
<b>All Dimensions in mm</b>			

**Suggested Pad Layout**

X1-DFN1006-3 (Type SA)



Dimensions	Value (in mm)
C	0.700
G	0.300
G1	0.200
X	0.400
X1	1.100
Y	0.250
Y1	0.700

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.